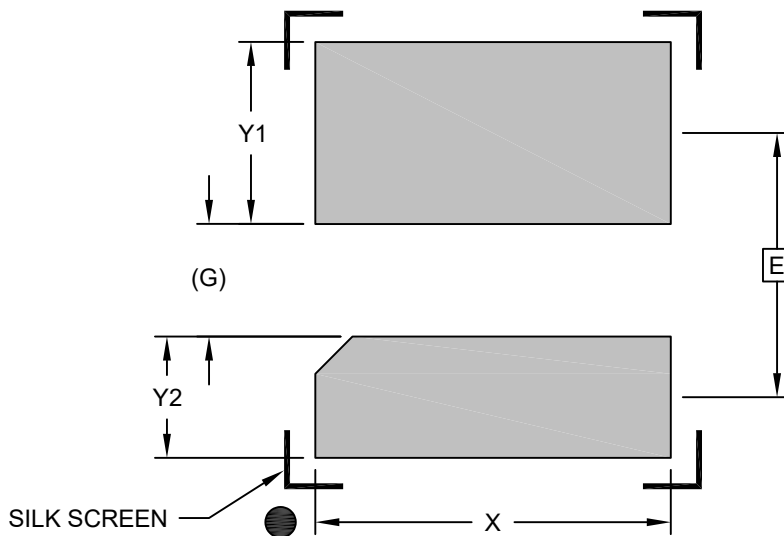


## 2-Lead Very Thin Single Flatpack No Lead Package (2EW) - 2.0x2.35x0.9 mm Body [VSFN]

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



### RECOMMENDED LAND PATTERN

		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Contact Pitch	E		1.525 BSC		
Contact Pad Length (X2)	X				2.10
Contact Pad Width	Y1				1.05
Contact Pad Width	Y2				0.70
Contact Pad to Center Pad (Xnn)	G		0.587 REF		

#### Notes:

- Dimensioning and tolerancing per ASME Y14.5M  
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
- For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process